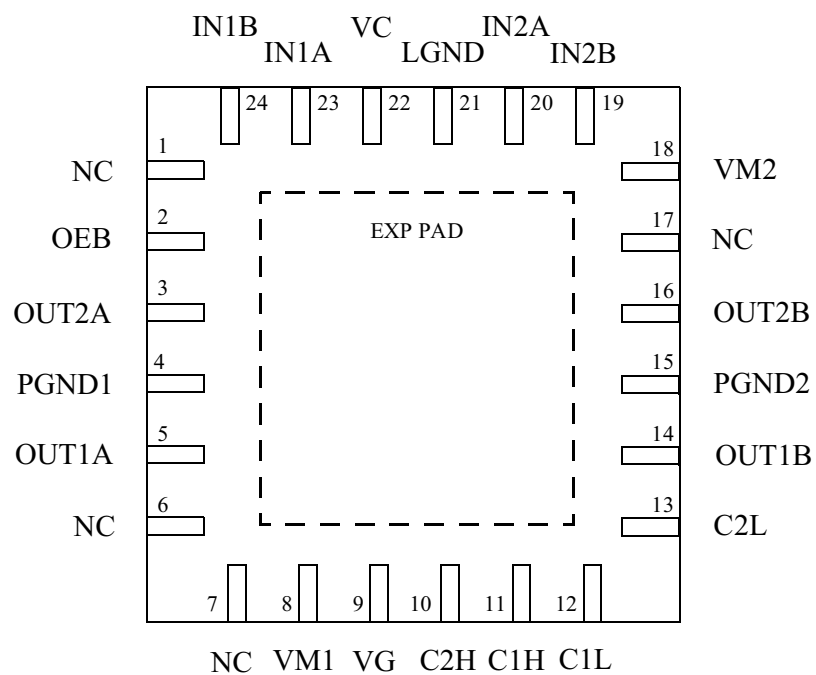


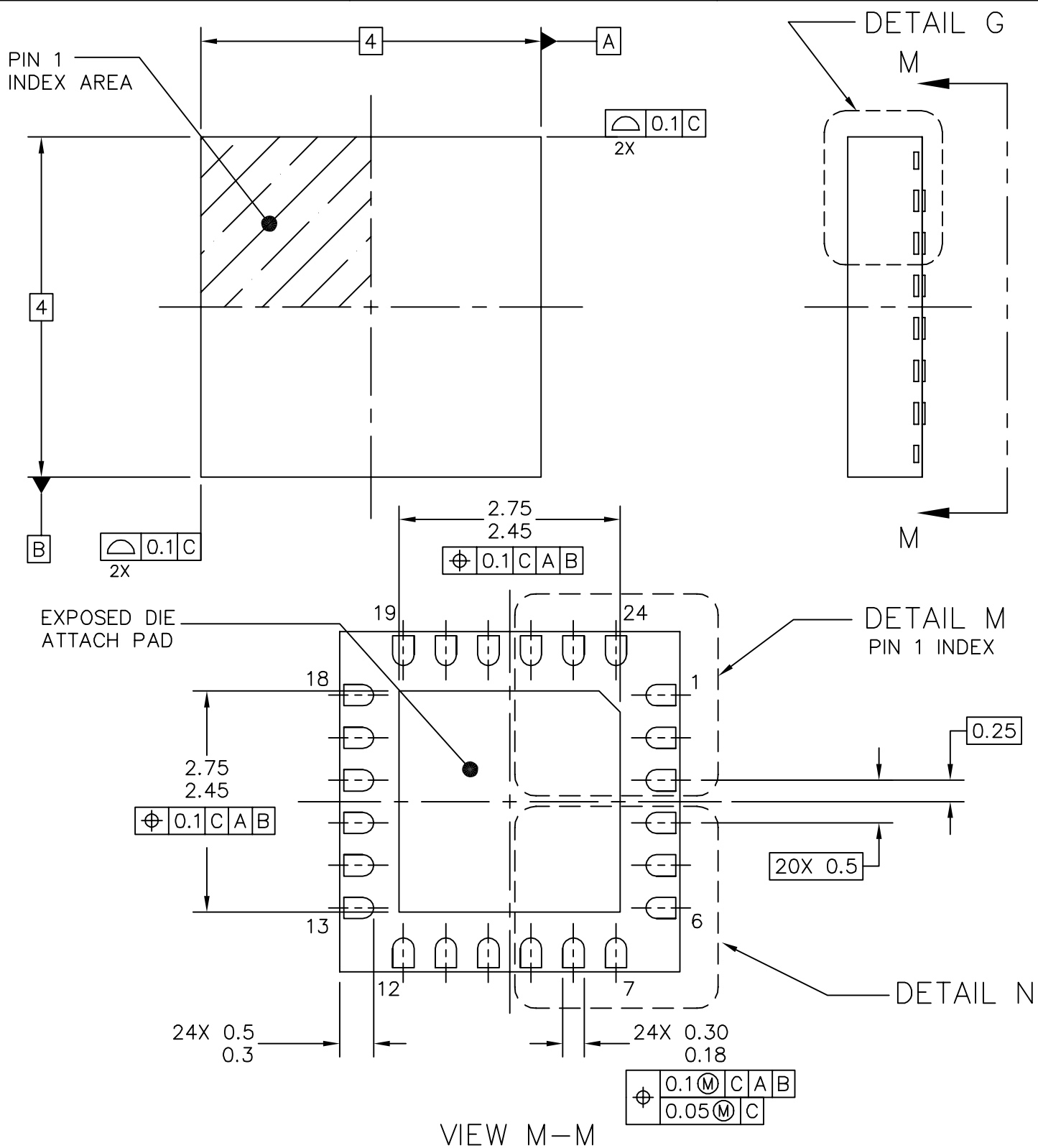
MPC17259EP (QFN24PIN) ピン配置図



TOP VIEW

DO NOT SCALE THIS DRAWING

REV: 0



TITLE: THERMALLY ENHANCED QUAD
FLAT NON-LEADED PACKAGE (QFN)
24 TERMINAL, 0.5 PITCH (4 X 4 X 1)

CASE NUMBER: 1508-01

STANDARD: MOT STD

PACKAGE CODE: 6135

SHEET: 1 OF 4

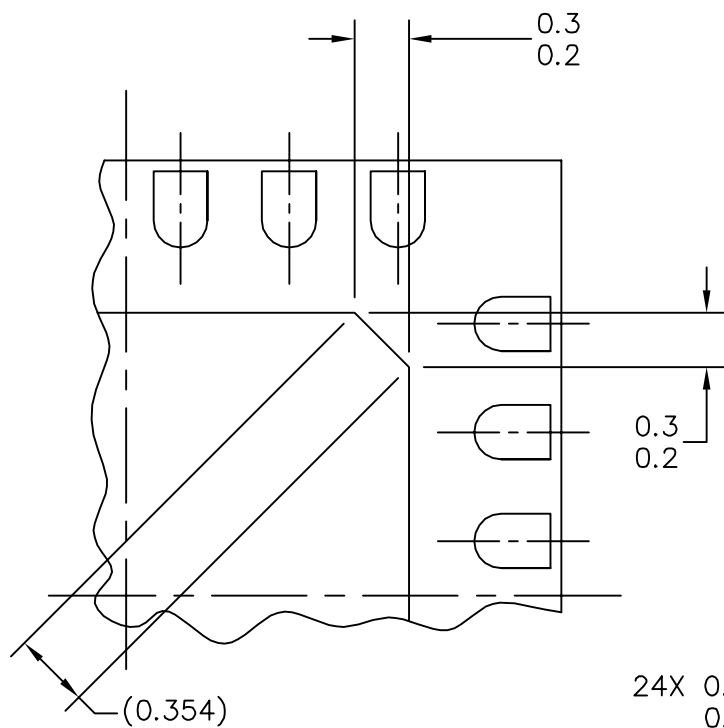
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DICTIONARY**

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DOCUMENT NO: 98ARL10577D

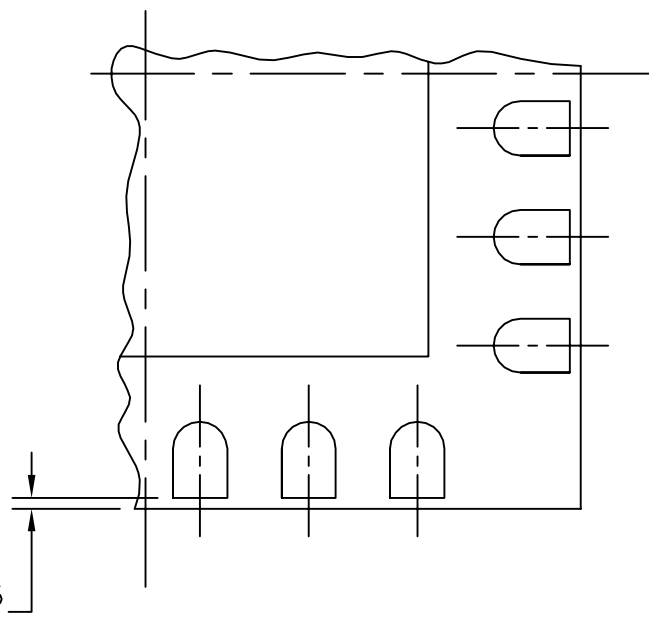
PAGE: 1508

REV: 0



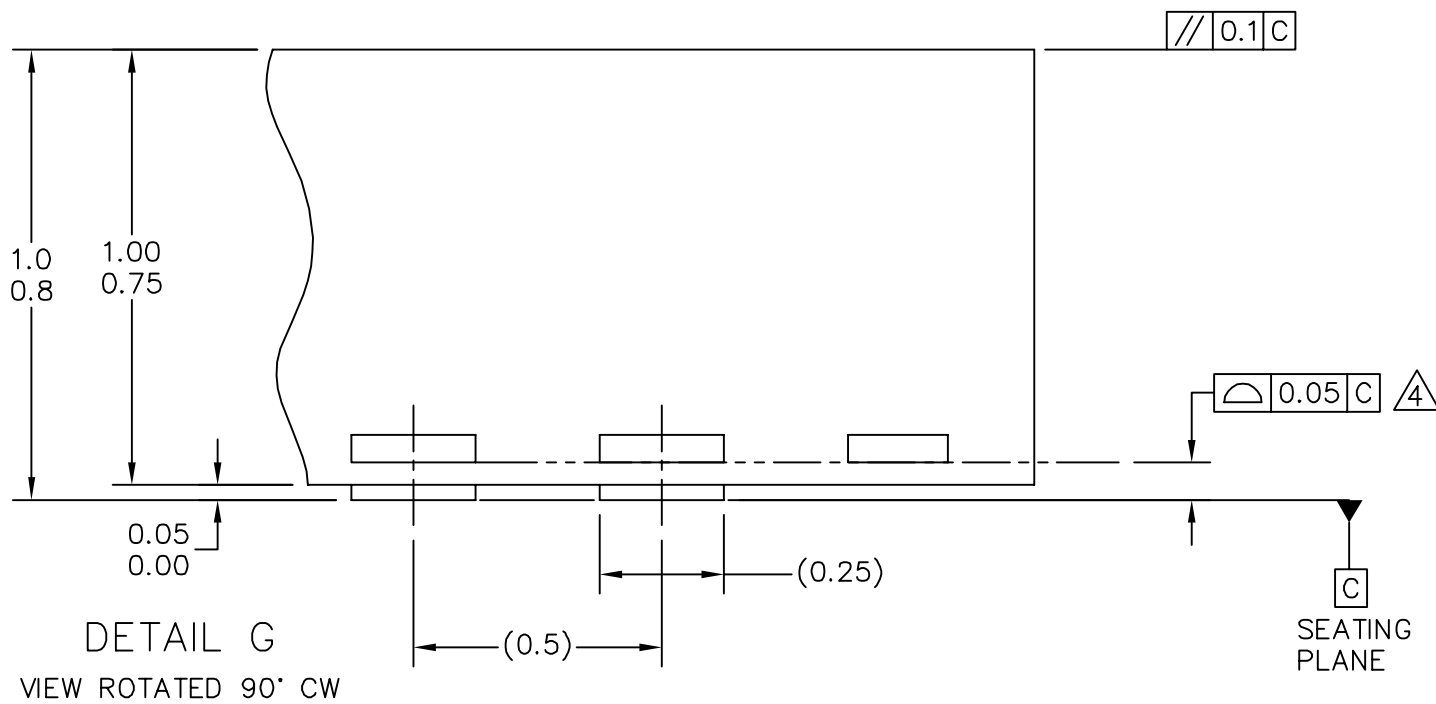
DETAIL M

PIN 1 BACKSIDE IDENTIFIER



DETAIL N

CORNER CONFIGURATION



DETAIL G

VIEW ROTATED 90° CW

TITLE: THERMALLY ENHANCED QUAD
FLAT NON-LEADED PACKAGE (QFN)
24 TERMINAL, 0.5 PITCH (4 X 4 X 1)

CASE NUMBER: 1508-01

STANDARD: MOT STD

PACKAGE CODE: 6135

SHEET: 2 OF 4

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**MECHANICAL OUTLINES
DICTIONARY**

DOCUMENT NO: 98ARL10577D

PAGE: 1508

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REV: 0

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFP-N.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.

TITLE: THERMALLY ENHANCED QUAD
FLAT NON-LEADED PACKAGE (QFN)
24 TERMINAL, 0.5 PITCH (4 X 4 X 1)

CASE NUMBER: 1508-01

STANDARD: MOT STD

PACKAGE CODE: 6135

SHEET: 3 OF 4